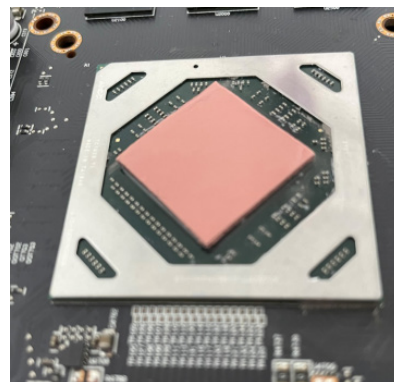


TGP3000SF

Silicone Free Thermally Conductive Gap Pad



BENEFITS AND FEATURES

- 3.0W/m.K thermal conductivity
- Excellent wettability to reduce contact resistance
- Silicone free, no contamination to electronics, especially to optical module
- Low volatile
- Low oil bleeding

OVERVIEW

Honeywell TGP3000SF is a non-silicone base thermal gap pad. It provides 3.0W/m.K thermal performance with good wettability to many substrates. TGP3000SF is low volatile type gap pad and designed for those electronic devices, which are sensitive to siloxane contamination.

TYPICAL APPLICATIONS

- Optical module
- Telecommunication equipment
- LCD, LED and projectors
- SSD
- Camara modules

STORAGE & USE

Shelf Life 12 months at 0-35°C, <65%RH

Property	TGP3000SF	Test Method
Color	Pink	By visual
Thermal Conductivity (W/m.K)	3.0	ASTM D5470
Thermal Impedance (in ² .K/W) (1mm@10psi)	0.55	ASTM D5470
Specific gravity	3.1	ASTM D792
Hardness (Shore 00)	50	ASTM D2240
Volatile content (TML%)	0.2	ASTM E595
Volatile content (CVCm%)	0.02	ASTM E595
Dielectric constant @1MHz	6.2	ASTM D150
Volume resistivity (Ohm.cm)	1.0x10 ¹⁴	ASTM D257
Flame retardancy	V-0	UL 94 equivalent

Honeywell Electronic Materials

USA: 1-509-252-2102
 Mainland China: 400-842-8487
 Germany: 49-5137-999-9199
 Japan: 81-3-6730-7092
 Korea: 82-2-3483-5076
 Singapore: 65-6580-3593
 Taiwan: 886-3-6580300 ext.312
www.electronicmaterials.com

Although all statements and information contained herein are believed to be accurate and reliable, they are presented without guarantee or warranty of any kind, express or implied. Information provided herein does not relieve the user from the responsibility of carrying out its own tests and experiments, and the user assumes all risks and liability for use of the information and results obtained. Statements or suggestions concerning the use of materials and processes are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should not assume that all toxicity data and safety measures are indicated herein or that other measures may not be required.